

GL Silicon N-Channel Power MOSFET

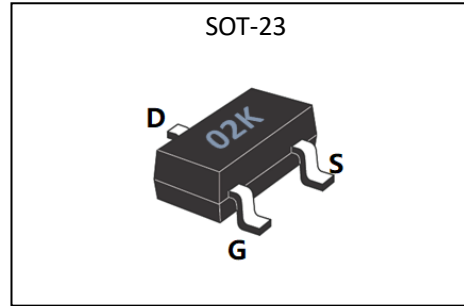
General Description

The GL2N7002K uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications. The package form is SOT-23, which accords with the RoHS standard.

V_{DSS}	60	V
I_D	0.3	A
P_D	0.35	W
$R_{DS(ON)max}$	2.5	Ω

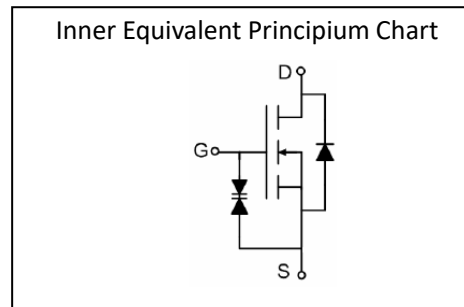
Features

- Fast Switching
- Low Gate Charge and R_{dson}
- Low Reverse transfer capacitances
- 100% Single Pulse avalanche energy Test



Applications

- PWM applications
- Load switch
- Power management



Absolute (Tc=25°C unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-to-Source Voltage	60	V
I_D	Continuous Drain Current	0.3	A
	Continuous Drain Current $T_C = 100^\circ\text{C}$	0.19	A
I_{DM}^{a1}	Pulsed Drain Current	0.9	A
V_{GS}	Gate-to-Source Voltage	± 20	V
dv/dt^{a3}	Peak Diode Recovery dv/dt	5.0	V/ns
P_D	Power Dissipation	0.35	W
VESD(G-S)	Gate source ESD (HBM-C= 100pF, R=1.5k Ω)	2000	V
T_J, T_{stg}	Operating Junction and Storage Temperature Range	150, -55 to 150	$^\circ\text{C}$
T_L	Maximum Temperature for Soldering	300	$^\circ\text{C}$

Caution Stresses greater than those in the "Absolute Maximum Ratings" may cause permanent damage to the device

**GL Silicon N-Channel Power MOSFET****Electrical Characteristics** (Tc= 25°C unless otherwise specified)

OFF Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
V_{DSS}	Drain to Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	60	--	--	V
$\Delta BV_{DSS}/\Delta T_J$	Bvdss Temperature Coefficient	$I_D=-250\mu A$, Reference 25°C	--	0.1	--	V/°C
I_{DSS}	Drain to Source Leakage Current	$V_{DS}=60V, V_{GS}=0V, T_a=25^\circ C$	--	--	1	μA
		$V_{DS}=48V, V_{GS}=0V, T_a=125^\circ C$	--	--	250	
$I_{GSS(F)}$	Gate to Source Forward Leakage	$V_{GS}=+20V$	--	--	10	μA
$I_{GSS(R)}$	Gate to Source Reverse Leakage	$V_{GS}=-20V$	--	--	-10	μA

ON Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$R_{DS(ON)}$	Drain-to-Source On-Resistance	$V_{GS}=10V, I_D=0.5A$	--	--	2.5	Ω
$R_{DS(ON)}$	Drain-to-Source On-Resistance	$V_{GS}=4.5V, I_D=0.3A$	--	--	3.5	Ω
$V_{GS(TH)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.7	2.5	V
Pulse width $t_p \leq 380\mu s, \delta \leq 2\%$						

Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
g_{fs}	Forward Transconductance	$V_{DS}=10V, I_D=0.2A$	0.1	5.0	--	S
C_{iss}	Input Capacitance	$V_{GS}=0V, V_{DS}=15V$ $f=1.0MHz$	--	20	--	pF
C_{oss}	Output Capacitance		--	12	--	
C_{rss}	Reverse Transfer Capacitance		--	4.4	--	

Resistive Switching Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$t_{d(ON)}$	Turn-on Delay Time	$I_D=0.2A, V_{DD}=15V$ $V_{GS}=10V, R_G=3.0\Omega$	--	10	--	ns
t_r	Rise Time		--	45	--	
$t_{d(OFF)}$	Turn-Off Delay Time		--	15	--	
t_f	Fall Time		--	10	--	
Q_g	Total Gate Charge	$I_D=0.3A, V_{DD}=15V$ $V_{GS}=10V$	--	1.7	--	nC
Q_{gs}	Gate to Source Charge		--	0.9	--	
Q_{gd}	Gate to Drain ("Miller") Charge		--	1.3	--	



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Source-Drain Diode Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
I_S	Continuous Source Current (Body Diode)		--	--	0.3	A
I_{SM}	Maximum Pulsed Current (Body Diode)		--	--	0.9	A
V_{SD}	Diode Forward Voltage	$I_S=0.3A, V_{GS}=0V$	--	--	1.5	V
t_{rr}	Reverse Recovery Time	$I_S=0.3A, T_j = 25^{\circ}C$	--	40	--	ns
Q_{rr}	Reverse Recovery Charge	$di_F/dt=100A/us, V_{GS}=0V$	--	120	--	nC
Pulse width $t_p \leq 380\mu s, \delta \leq 2\%$						

Thermal Characteristics

Symbol	Parameter	Typ.	Units
$R_{\theta JA}$	Junction-to-Ambient	350	$^{\circ}C/W$

^{a1}: Repetitive rating; pulse width limited by maximum junction temperature

^{a3}: $I_{SD}=0.3A, di/dt \leq 100A/us, V_{DD} \leq BV_{DS}$, Start $T_j=25^{\circ}C$

Typical Electrical And Thermal Characteristics

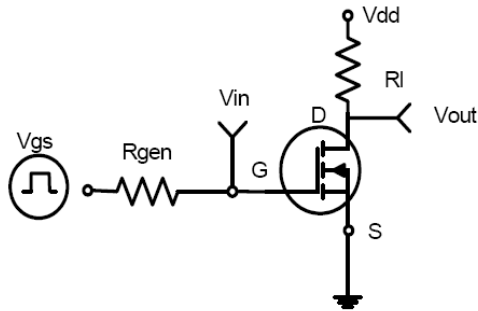


Figure 1: Switching Test Circuit

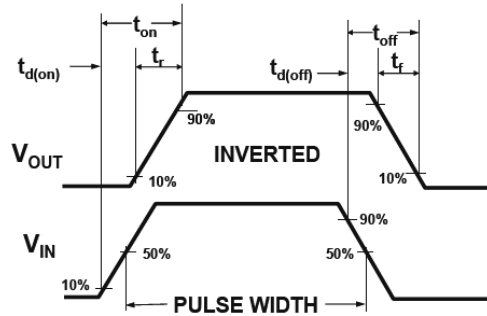


Figure 2: Switching Waveforms

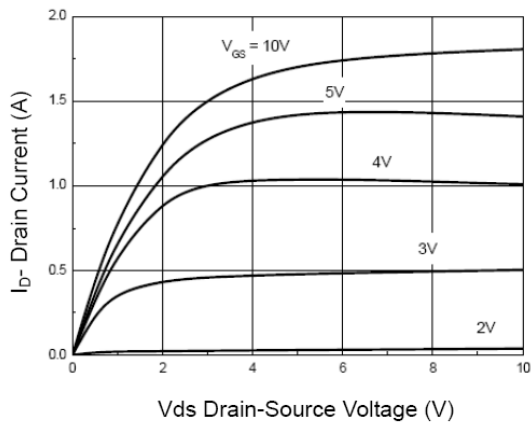


Figure 3 Output Characteristics

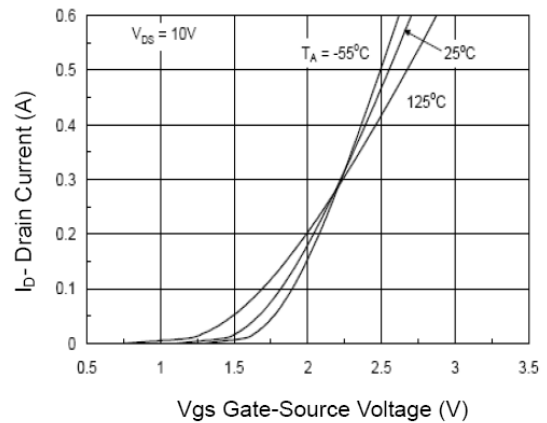


Figure 4 Transfer Characteristics

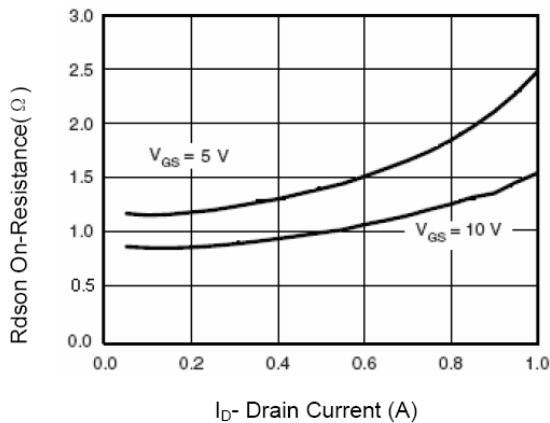


Figure 5 Drain-Source On-Resistance

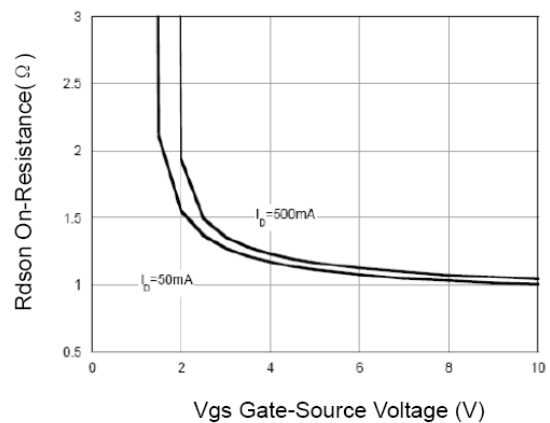


Figure 6 Rdson vs Vgs

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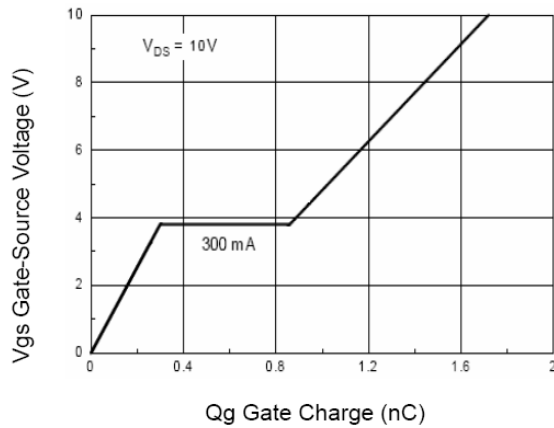


Figure 7 Gate Charge

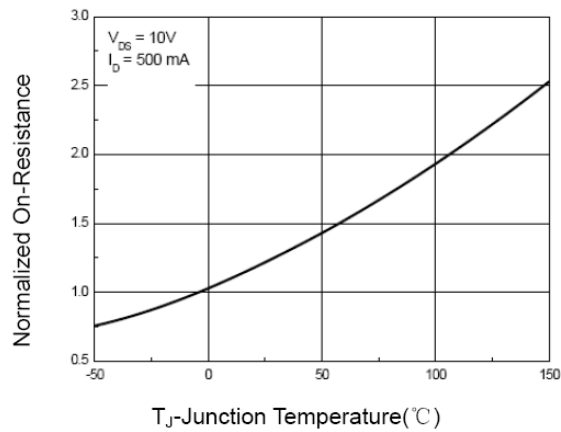


Figure 9 Drain-Source On-Resistance

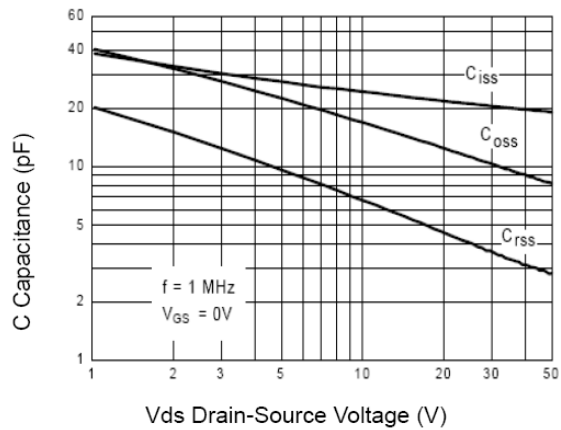


Figure 11 Capacitance vs Vds

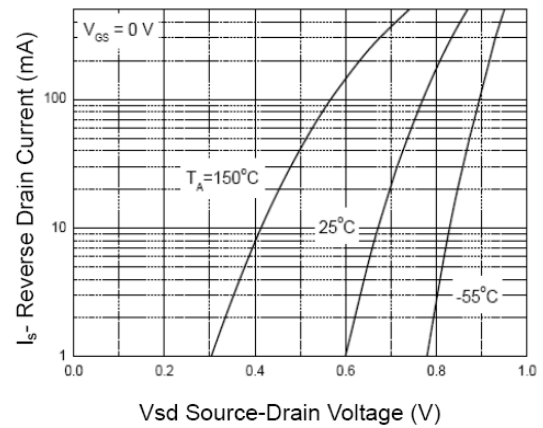


Figure 8 Source-Drain Diode Forward

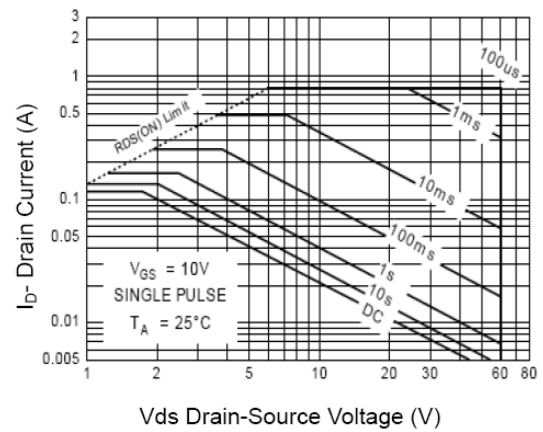


Figure 10 Safe Operation Area

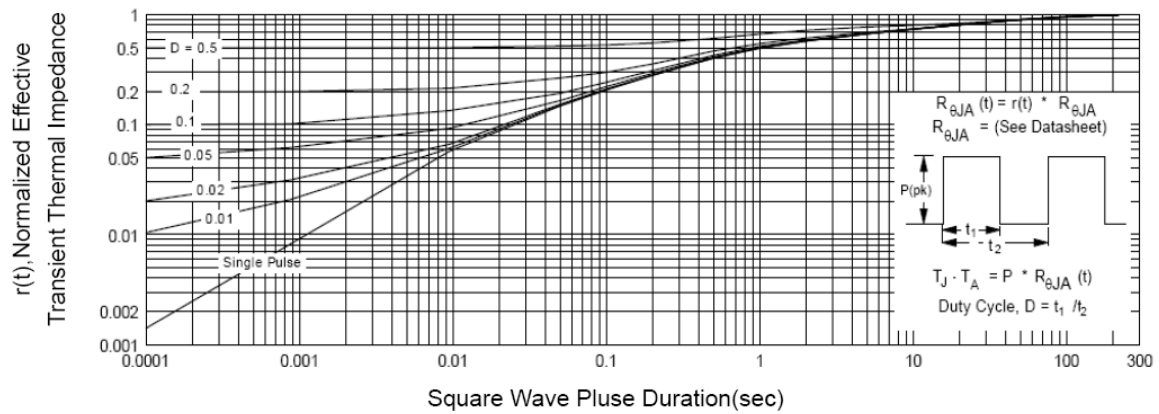


Figure 12 Normalized Maximum Transient Thermal Impedance

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